

What is claimed is:

1. A process, comprising:
performing certain process steps from the top side of a substrate carrying a plurality of devices, at least certain of the devices having a micro-machined mesh;
attaching a carrier wafer to the top of the substrate;
reducing the thickness of the substrate; and
continuing the process of fabricating the plurality of devices from the back side of the substrate.
2. The process of claim 1 wherein said performing includes forming and patterning a layer of resist.
3. The process of claim 1 wherein said performing includes forming a plurality of meshes.
4. The process of claim 1 wherein said continuing includes forming vent holes.
5. The process of claim 4 additionally comprising attaching a carrier wafer to the back side of the substrate and removing the carrier wafer from the top side of the substrate, said process additionally comprising forming and releasing a plurality of meshes from the top side of the substrate.
6. The process of claim 5 additionally comprising singulating the plurality of devices.
7. A process, comprising:
attaching a carrier wafer to a top side of a substrate carrying a plurality of devices, at least certain of said devices including a mesh;
reducing the thickness of said substrate;
performing process steps from the back side of said substrate;
attaching a carrier wafer to the back side of said substrate and removing said carrier wafer from the top side of said substrate; and
performing process steps from the top side of said substrate.
8. The process of claim 7 wherein said performing process steps from the back side of the substrate includes forming vent holes.
9. The process of claim 7 wherein said performing process steps from the top side of said substrate includes forming and releasing a plurality of meshes.

10. The process of claim 9 additionally comprising singulating the plurality of devices.

11. In a process for fabricating a MEMS device, the improvement comprising:

reducing the thickness of a substrate; and

attaching a carrier wafer to one of the top side and back side of the substrate for use during at least a part of the process of fabricating the MEMS device.

12. In a process for fabricating a MEMS device, the improvement comprising:

reducing the thickness of a substrate carrying a plurality of devices;

using a carrier wafer attached to the top side of said substrate while at least certain process steps are performed from the back side; and

using a carrier wafer attached to the back side of said substrate while at least certain process steps are performed from the top side.